| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|----------|------|--|---|---------------------|---------|------------------|
| L1 | 11 | (("6333559") or ("6376279") or ("6541844") or ("6465867") or ("6204165")).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/02/04 08:49 |
| L2 | 2 | ("6211572").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/02/04 08:49 |
| L3 | 1 | "5874782".PN. | USPAT; USOCR | OR | ON | 2005/02/04 08:50 |
| L4 | 1 | "5777379".PN. | USPAT; USOCR | OR | ON | 2005/02/04 08:52 |
| L5 | 1 | "5679977".PN. | USPAT; USOCR | OR | ON | 2005/02/04 08:57 |
| L7 | 233 | @ad<="20031230" and 'compliant' with 'packaging' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/04 08:58 |
| L8 | 92 | @ad<="20031230" and 'bonding pad' and 'compliant' with 'package' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/04 08:59 |
| L9 | 2 | @ad<="20031230" and 'bonding pad' same 'compliant' with 'packaging' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/04 08:59 |
| S1 | 9 | ("5796163" "6201305" "6586676" " 6624504").PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 12:02 |
| S2 | 6859 | @ad<="20031230" and (257/668). ccls. or (257/737-738).ccls. or (257/780-781).ccls. or (257/E21. 503).ccls. or (257/E23.119).ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:34 |
| S3 | 5226 | @ad<="20031230" and (257/734). ccls. or (257/784).ccls. or (257/779).ccls. or (257/786).ccls. or (257/792).ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 12:17 |
| S4 | 1 | @ad<="20031230" and (257/668). ccls. and 'solder contact' same 'pad' same 'flexible' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 13:36 |

| S5 | 1 | @ad<="20031230" and (257/668). ccls. and 'bonding pad' same | US-PGPUB; USPAT; | OR | ON | 2005/02/03 13:37 |
|-----|----|---|---|----|------|------------------|
| | | 'modulus' | EPO; JPO; DERWENT; IBM_TDB | | | |
| S6 | 44 | @ad<="20031230" and (257/668). ccls. and 'bonding pad' same 'flexible' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 13:41 |
| S7 | 3 | @ad<="20031230" and (257/668). ccls. and 'bonding pad' same 'compliant layer' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/04 08:57 |
| S8 | 1 | "6147401".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:45 |
| S9 | 1 | "6043563".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:47 |
| S10 | 1 | "5885849".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:48 |
| S11 | 1 | "4736236".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:52 |
| S12 | 1 | "4670770".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:52 |
| S13 | 1 | "4612566".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:53 |
| S14 | 1 | "4527330".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:53 |
| S15 | 1 | "4413308".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:53 |
| S16 | 1 | "4232512".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:54 |
| S17 | 1 | "4215359".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:56 |
| S18 | 1 | "4200975".PN. | USPAT; USOCR | OR | ON . | 2005/02/03 13:56 |
| S19 | 4 | @ad<="20031230" and (257/668). ccls. and 'bonding pad' same 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON . | 2005/02/03 14:05 |
| S20 | 1 | "6147401".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:58 |
| S21 | 1 | "6043563".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:58 |
| S22 | 1 | "5929517".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:58 |
| S23 | 1 | "5885849".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:59 |
| S24 | 1 | "5749997".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:59 |

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C:\Documents and Settings\TLe10\My Documents\EAST\Workspaces\Packaging, Flip Chip, BGA, Solder Ball, Bonding Pad, and Test

| S25 | 1 | "5679977".PN. | USPAT; USOCR | OR | ON | 2005/02/03 14:00 |
|-----|-----|---|---|------|----|------------------|
| S26 | 1 | "5666270".PN. | USPAT; USOCR | OR | ON | 2005/02/03 14:01 |
| S27 | 1 | "5180311".PN. | USPAT; USOCR | OR | ON | 2005/02/03 14:02 |
| S28 | 1 | @ad<="20031230" and (257/668). ccls. and 'bonding pad' same 'Resilient' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:08 |
| S29 | 3 | @ad<="20031230" and (257/668). ccls. and 'pad' same 'compliance' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:09 |
| S30 | 111 | @ad<="20031230" and 'bonding pad' same 'Resilient' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:09 |
| S31 | 12 | @ad<="20031230" and 'bonding pad' same 'Resilience' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:09 |
| S33 | 30 | @ad<="20031230" and (257/668). ccls. and 'pad' same 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 15:04 |
| S34 | 44 | @ad<="20031230" and 'bonding pad' same 'compliance' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR . | ON | 2005/02/03 14:10 |
| S35 | 136 | @ad<="20031230" and 'bonding pad' same 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:10 |
| S36 | 3 | @ad<="20031230" and 'solder contact' same 'pad' same 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:11 |
| S37 | 919 | @ad<="20031230" and 'pad' with 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 15:44 |

| S38 | 11 | @ad<="20031230" and 'solder' and 'pad' with 'different' with 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:13 |
|-----|------|--|---|----|----|------------------|
| S39 | 3685 | @ad<="20031230" and (257/668). ccls. or (257/737-738).ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:34 |
| S40 | 1 | "6049130".PN. | USPAT; USOCR | OR | ON | 2005/02/03 14:35 |
| S41 | 1 | "6034431".PN. | USPAT; USOCR | OR | ON | 2005/02/03 14:36 |
| S42 | 570 | @ad<="20031230" and 'compliant contact' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 15:05 |
| S43 | 74 | @ad<="20031230" and 'solder ball' and 'compliant contact' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 15:05 |
| S44 | 1 | "6333563".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:18 |
| S45 | 1 | "6221697".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:19 |
| S46 | 1 | "6443351".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:22 |
| S47 | 1 | "6409073".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:23 |
| S48 | 1 | "6396156".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:23 |
| S49 | 1 | "6369451".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:24 |
| S50 | 1 | "6333104".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:24 |
| S51 | 20 | @ad<="20031230" and 'bonding pad' with 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 15:44 |
| S53 | 219 | @ad<="20031230" and 'bonding pad' and 'solder ball' and 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 15:45 |
| S54 | 81 | @ad<="20031230" and 'bonding pad' and 'solder ball' and 'compliant layer' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 15:45 |